

Datasheet: 110317-W01

Etching

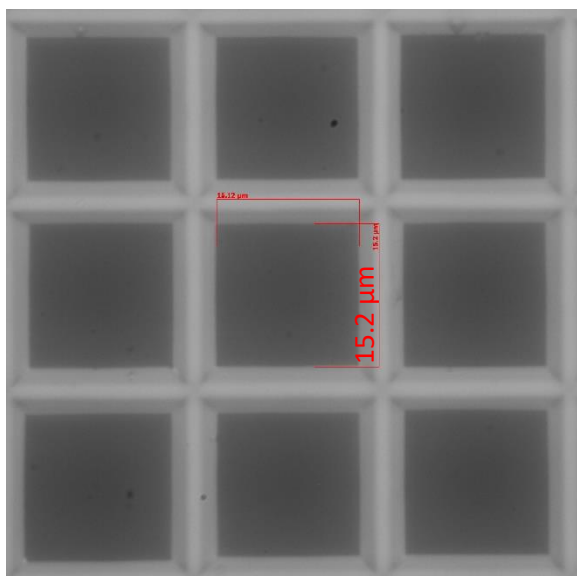
Size:	6 inch
Pitch:	20 μm square
Length:	375 μm
Shape:	straight
Diameter:	9 μm

Postprocessing

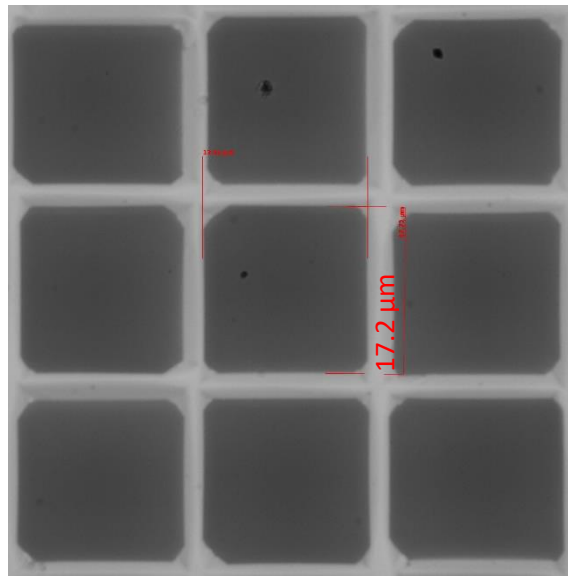
- Substrate removal \rightarrow 325 μm (membrane thickness)
- Anisotropic pore widening \rightarrow 17-18 μm (back side)
- Laserdicing 10 x 10 mm

Measurements

Front side view



Back side view



Please note: Most Wafers have a short bottleneck close below the front side. Thus the real porosity of the porous membrane has to be characterized by gravimetric measurements instead of surface microscopy! These images are just as a reference for differences of the surface morphology.